

AMENDMENTS TO THE CLAIMS

1. (Currently amended) A molded product comprising a dielectric constant of 3.0 or less and a dielectric dissipation factor of 0.04 or less obtained by the injection molding of a wholly aromatic liquid crystal polyester resin composition which comprises 45 to 90 percent by weight of a wholly aromatic liquid crystal polyester having a melting point of 320°C or more, 10 to 40 percent by weight of an inorganic spherical hollow material having an aspect ratio of 2 or less, and 0 to 15 percent by weight (100 percent by weight as a total) of an inorganic filler having an aspect ratio of 4 or more, and wherein the apparent viscosity of the liquid crystal polyester at a temperature of 20°C above the melting point of the liquid crystal polyester is 5,000 poise or less, and wherein the fracture rate X of the inorganic spherical hollow material is 0.045 to 0.094 using the following equation:

$\rho = 100 / [\alpha/\rho_1 + \beta/\rho_2 + \gamma(1 - X)/\rho_3 + \gamma X/\rho_4]$, where in the equation:

α = the percent by weight of the wholly aromatic liquid crystal polyester resin;

β = the percent by weight of the inorganic filler having an aspect ratio of 4 or more;

y = the percent by weight of the inorganic spherical hollow material having an aspect ratio of 2 or less;

ρ = the specific gravity of the wholly aromatic liquid crystal polyester resin composition;

ρ_1 = the specific gravity of the wholly aromatic liquid crystal polyester resin;

ρ_2 = the specific gravity of the inorganic filler having an aspect ratio of 4 or more;

ρ_3 = the true specific gravity of the inorganic spherical hollow material having an aspect ratio of 2 or less;

ρ_4 = the material specific gravity of the inorganic spherical hollow material;

X = the fracture rate of the inorganic spherical hollow material;

$y(1 - X)$ = the percent by weight of non-fractured inorganic spherical hollow material;

yX = the percent by weight of fractured inorganic spherical hollow material.

2. (Previously presented) The molded product according to claim 1, wherein said wholly aromatic liquid crystal polyester is

prepared by the polycondensation of 80 to 100 percent by mole of p-hydroxy benzoic acid (I), terephthalic acid (II), and 4,4'-dihydroxy diphenyl (III) (including the derivatives) (provided that the total of (I) and (II) is more than 60 mole percent) and 0 to 20 percent by mole of other aromatic compound which can conduct a decondensation reaction with any one of (I), (II), or (III).

3. (Cancelled)

4. (Previously presented) The molded product according to claim 1, wherein the above mentioned inorganic spherical hollow material having an aspect ratio of 2 or less is an average particle diameter of 5 to 200 μm , and a rate of volume hollowness of 50 percent or more.

5. (Previously presented) The molded product according to claim 1, wherein the inorganic filler having an aspect ratio of 4 or more is a glass fiber having an average diameter of 20 μm or less and/or talc having an average particle diameter of 100 μm or less and additionally the weight percent is in a range of 5 to 15.

6. (Previously presented) The molded product according to claim 1, wherein the molded product comprises a portion having a thickness of 0.5mm or less and comprising a relative dielectric constant of said portion of 3 or less.

7. (Previously presented) The molded product according to claim 1, comprising a portable wireless telecommunications equipment having said molded product as a fixing or a holding member of a transmitting and receiving component.

8. (Previously presented) The molded product according to claim 2, wherein:

the above mentioned inorganic spherical hollow material having an aspect ratio of 2 or less is an average particle diameter of 5 to 200 μm , and a rate of volume hollowness of 50 percent or more; and

the inorganic filler having an aspect ratio of 4 or more is a glass fiber having an average diameter of 20 μm or less and/or talc having an average particle diameter of 100 μm or less and additionally the weight percent is in a range of 5 to 15.

9. (Previously presented) The molded product according to claim 8, comprising:

a portion of the molded product having a thickness 0.5mm or less and comprising a relative dielectric constant of said portion of 3 or less; and

a portable wireless telecommunications equipment having said molded product as a fixing or a holding member of a transmitting and receiving component.